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U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICESUPPLEMENTAL INFORMATION  
DISCLOSURE STATEMENTDocket Number:  
**10191/3268**Application Number  
**10/655,839**Filing Date  
**Sept. 4, 2003**Examiner  
**Dung Anh LE**Art Unit  
**2818**

Invention Title

**SEMICONDUCTOR COMPONENT HAVING A  
FIRST EARLIER STRUCTURE DIFFERING  
FROM A SECOND EARLIER STRUCTURE**

Inventors

**Hubert BENZEL et al.**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

1. In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and in conformance with the procedures of 35 U.S.C. §§ 1.97 and 1.98 and M.P.E.P. § 609, attorneys for Applicant hereby bring the following references to the attention of the Examiner. These references are listed on the attached modified PTO Form No. 1449. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom. The filing of this Information Disclosure Statement and the enclosed PTO Form No. 1449, shall not be construed as an admission that the information cited is prior art, or is considered to be material to patentability as defined in 37 C.F.R. § 1.56(b).
2. A copy of the references listed on the modified PTO Form 1449 are enclosed herewith or as otherwise indicated.
3. Applicant's attorney certifies that each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of information disclosure statement.

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This correspondence is being deposited with the  
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Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450

RR

Date: 8/11/05

Signature: Cathy Egan

4. The Commissioner is hereby authorized to charge payment of the 37 C.F.R. §1.17(p) (submission of an information disclosure statement under §1.97(c)) fee of \$180.00 and any additional fees that may be required to the deposit account of **Kenyon & Kenyon**, deposit account number 11-0600. A copy of this communication is enclosed for charging purposes.

Dated: 8/11/05

By:

  
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO. 10191/3268	SERIAL NO. 10/655,839
	APPLICANT Hubert Benzel et al.	
	FILING DATE Sept. 4, 2003	GROUP 2818

#### U. S. PATENT DOCUMENTS

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE*

\* - If pertinent

#### FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
	1 088 785	April 4, 2001	EP			YES	NO
	100 46 622	April 4, 2002	DE			X	
	WO 03/016203	Feb. 27, 2003	PCT			X	
	WO 02/36484	May 10, 2002	PCT			X	

#### OTHER DOCUMENTS

EXAMINER INITIAL		AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
		R.W Tjeskstra et al. "Multi-walled Microchannels: Free-standing Porous Silicon Membrane For Use in Mu TAS", Journal of Microelectromechanical Systems, IEEE INC., Bd. 9 Nr. 4, Dec. 2000, pp. 495-501.
		H. Artmann et L. "Monocrystalline Si Membranes For Pressure Sensors Fabricated By A Novel Surface Micromachining Process Using Porous Silicon", Proceedings of Spie, Memes Components and Applications for Industry, Automobiles, Aerospace and Communication II, January 28-29, 2003, San Jose, CA, Bd. 4981, pp. 65-70.
		G. Lammel et al. "Free-Standing, Mobile 3D Porous Silicon Microstructures", Sensors and Actuators A, Bd. 85, No. 1-3, August 25, 2000, pp. 356-360.

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	